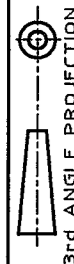


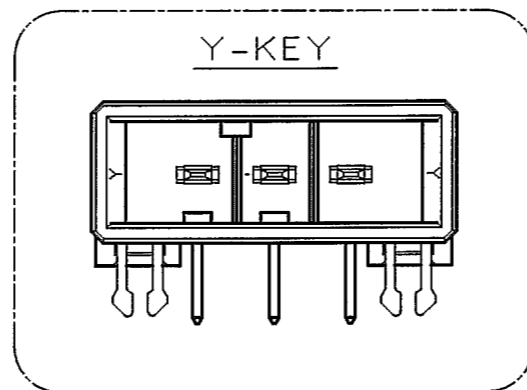
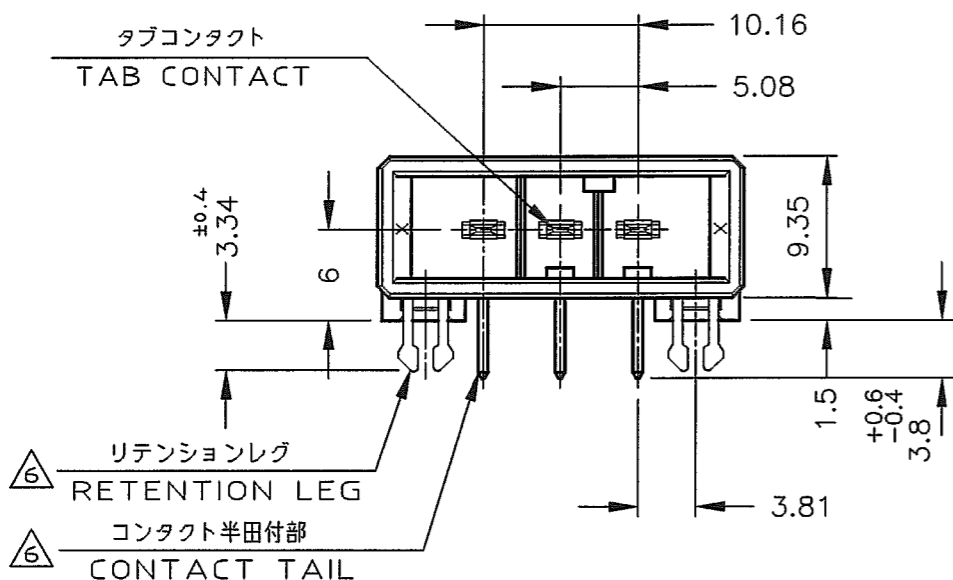
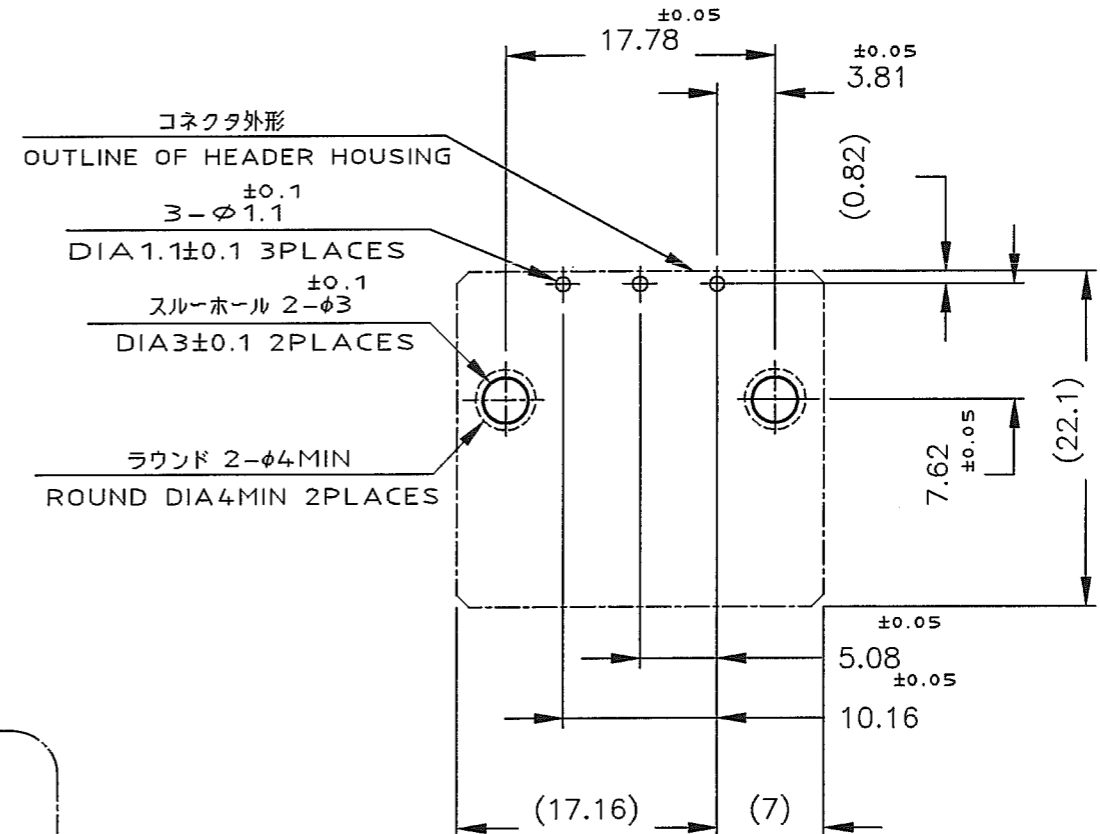
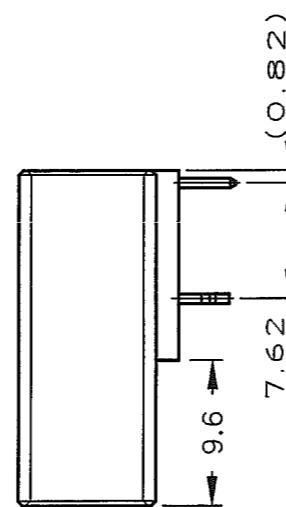
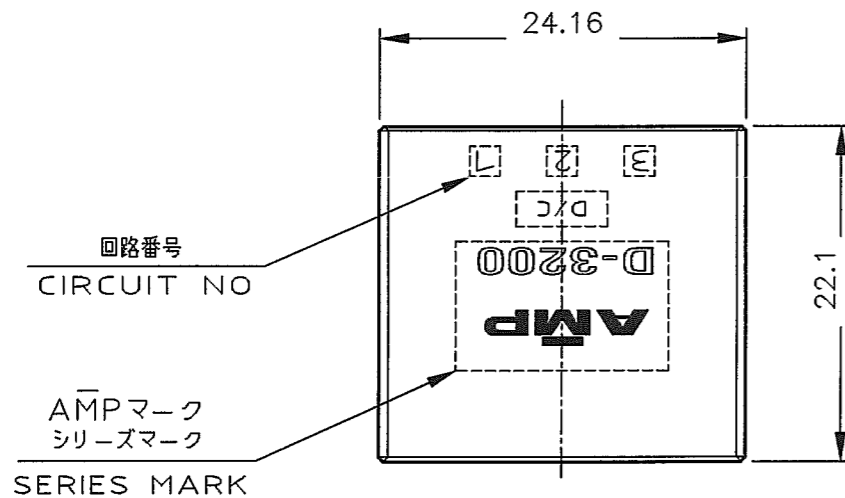
NUMBER 178138



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け寸法  
PC 基板厚: 1.6 ± 0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6 ± 0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂  
コンタクト: 銅合金  
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地  
接触部: 0.38 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地  
接触部: 0.76 μm MIN金めっき
- めっき: コンタクト: 全面Ni下地  
接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上にスズめっき

△6	△4	2-178138-5	Y
△6	△3	2-178138-3	Y
△6	△2	2-178138-2	Y
△6	△4	1-178138-5	X
△6	△3	1-178138-3	X
△6	△2	1-178138-2	X
(FINISH)		製品番号 (PART NO.)	KEY

E1	REVISED PER ECO-11-005030	RK	HMR	23MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm <sup>2</sup> (AWG - )		mmφ		3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 20/MAR/95 K.IKEDA		DE. 20/MAR/95 K.IKEDA		SIZE A3	LOC J
CHK. 23/MAR/95 S.MANABE		APP. 23/MAR/95 S.MANABE		NUMBER C-178138	SCALE 2-1
				REV. E1	SHEET 1 OF 1

